

PD 966 M

Polymer-SMT-Adhesive

Thermosetting Polymer-SMT-Adhesive for High-Speed Dispensing

Description

PD 966 M is a thermosetting single-component, solvent-free polymer adhesive, developed for the surface mounting of SMT components on to PCBs and bare substrates.

Based on the reliable SMT adhesive PD 955M, this material has been optimised to avoid stringing.

The rheology is adapted for high-speed-dispensing. It allows for very low Z-Height-returns - the height above the board that the dispense head will retract to upon completion of the dispense cycle.

Special advantages

- Very wide processing window, no tendency to string.
- Developed for high-speed dispensing, special for overhead pressure systems.
- Dispensing with very low Z-Height-return possible.
- Form stable glue dots.
- Excellent adhesion with standard and also with difficult-to-glue components.
- Low humidity absorption.
- Very high surface insulation resistance (SIR).

Physical characteristics

Colour:	pale red
Homogeneity:	no particles >50 µm
Adhesion:	≥ 25 N/mm ² at room temperature.

Processing

The adhesive is suitable for machine and manual dispensing.

Curing

The standard curing conditions are: 125 °C (257 °F) / 3'. Max. curing temperature should not be higher than 200 °C. The minimum* curing times are shown in the following list or graphic page 2.

125 °C (257 °F)	150 °C (302 °F)	180 °C (355 °F)
3'	1.5'	1'

* Optimal curing conditions depend on the curing oven.

Cleaning

Before curing:

The uncured adhesive can be removed with solvent based or water based cleaning materials. Recommendation: different Zestron types (Zestron HC) Please contact your local representative for more details.. The cleaned parts must be completely dry before installing them in the machine.

After curing:

Because of the known residual thermoplasticity of the cured adhesive, defective components can be easily replaced by heating (with hot air) the cured adhesive joint above 100 °C. After removing the component (torsion movement), the hot air should be focused on the remaining adhesive in order to remove it with a sharp tool.

Packing

The adhesives PD 966 M can be filled in various machine-specified syringes.

Storage

Storage time:

- 6 months in a refrigerator, at a storage temperature of 5 - 12 °C (40 - 54 °F).

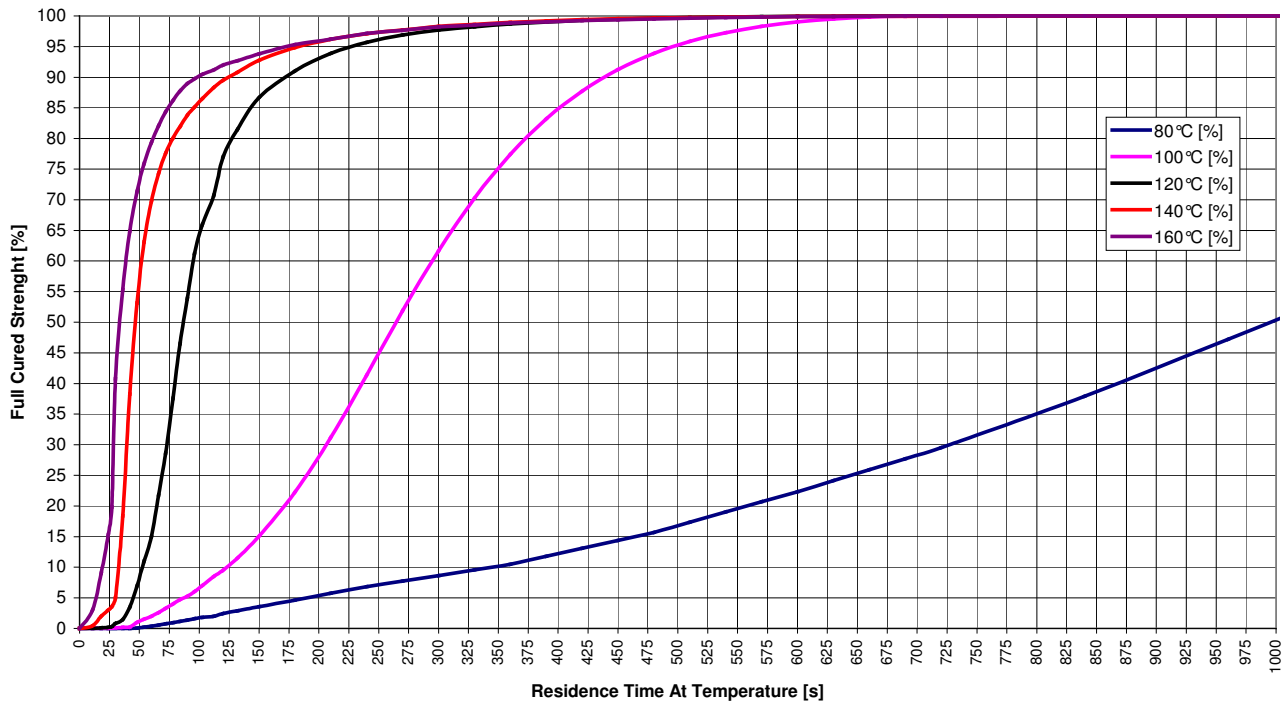
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Adhesion is sufficient at 85 % full cured strength

The descriptions and engineering data shown here have been compiled by Heraeus using commonly-accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for a particular application.

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